

MFP Film Capacitor

Material Data Sheet

Product Class	MFP Film Capacitors (Boxed) B32686_A	
Date	18/11/2019	
IMDS ID if available	NA	
Version	5.02.1a (03/2019)	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS** [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Heavy Metal	1C	Sn	6	7440-31-5	3	
	Heavy Metal	1C	Cu	17.5	7440-50-8	9	
	Heavy Metal	1C	Zn	12	7440-66-6	6	
	Light Metal	1B	Al	17.5	7429-90-5	9	
	Thermoplastic	2A	PP	47	9003-07-0	24	
Encapsulation	Duromer	2D	Epoxy	49		20	
	Thermoplastic	2A	PBT	36.5	26062-94-2	15	
	Flame Retardant	Not available	N,N Ethylene-bis(tetrabromophthalimide)	12	32588-76-4	5	
	Inorganic Solid	4A	Sb ₂ O ₃	2.5	1309-64-4	1	
Termination	Heavy Metal	1C	Cu	93.7	7440-50-8	7.5	
	Heavy Metal	1C	Sn	6.3	7440-31-5	0.5	
Sum in total:						100	

sizes w x h x l [mm]	weight range [g]	sizes w x h x l [mm]	weight range [g]	sizes w x h x l [mm]	weight range [g]	
12.0 x 22.0 x 42.0	18	16.0 x 28.5 x 42.0	25	20.0 x 39.5 x 41.5	40	B32686-A
14.0 x 25.0 x 42.0	20	18.0 x 32.5 x 41.5	32	20.0 x 39.5 x 42.0	40	
				28.0 x 42.5 x 41.5	60	

Not Part of a Product Class

Contact	Eduardo Perosa	Important remarks:
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<p>*) others: .(not declarable or prohibited substances acc. GADSL)</p> <p>**) typical mass percentage of substance</p>		

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (valid not valid)

no exemptions;

Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

Exemption 6 (b): Lead as an alloying element in aluminum containing up to 0,4 % lead by weight;

Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

Other Exemption than above